

Contactless Mobility Measurement

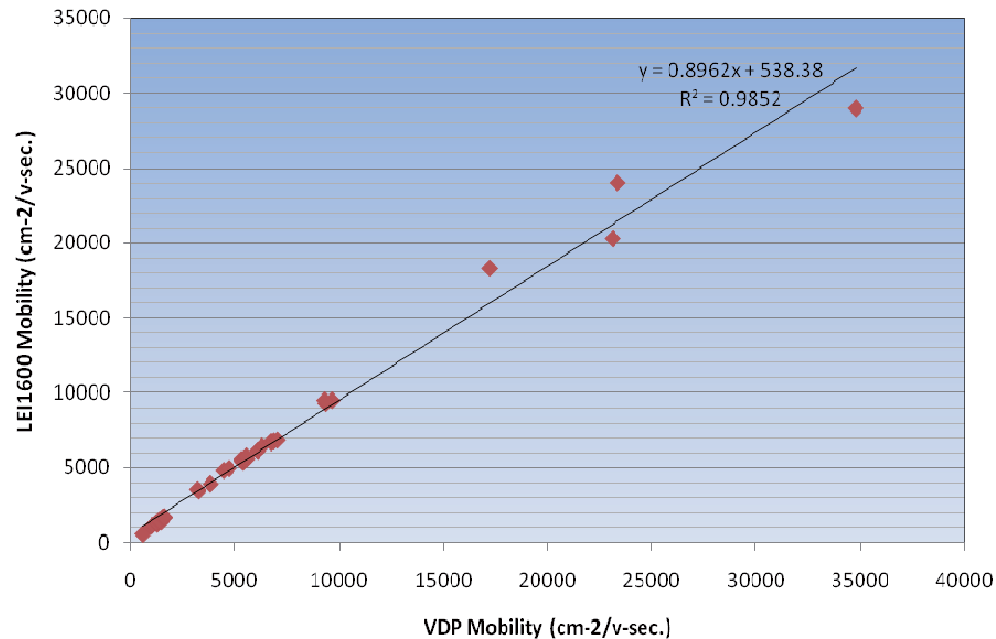
非接触迁移率测试系统

LEI Model 1605 could measure kinds of Semiconductor material and device structures , eliminate the need for time consuming sample preparation , mobility change caused by cleaving and contact making.

LEI Model 1605 ，是非接触迁移率测试系统，可对各种半导体材料和器件结构进行测试。无需制样，消除了样品制备引起的迁移率变化。

Capability:

- Fast , Non-destructive 快速，非破坏
- Hall Mobility 霍尔迁移率
- Sheet Resistance 方块电阻
- Improved repeatability提高测试的重复性
- Good correlation with VDP 与VDP法测试保持一致



Correlation of mobility data obtained by Van der Pauw Hall Measurements



LEI Model 1605